AVAGO TECHNOLOGIES, LTD. 4380 Ziegler Road Fort Collins, Colorado 80525

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE Inventor(s): R. Shane Fazzio Serial No.: 10/807,417 **Examiner: Monica Lewis** Filing Date: March 23, 2004 Group Art Unit: 2822 Title: Microcap Wafer Bonding Apparatus COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria VA 22313-1450 TRANSMITTAL LETTER FOR RESPONSE/AMENDMENT Sir: Transmitted herewith is/are the following in the above-identified application: Response/Amendment Petition to extend time to respond New fee as calculated below Supplemental Declaration No additional fee (Address envelope to "Mail Stop Amendments") ✓ Other: Response to Notice of Non-Compliant Amendment. (Fee S CLAIMS AS AMENDED BY OTHER THAN A SMALL ENTITY (1) FOR (3) NUMBER (4) HIGHEST NUMBER (5) PRESENT CLAIMS REMAINING ADDITIONAL RATE AFTER AMENDMENT PREVIOUSLY PAID FOR **EXTRA** EXTRA FEES TOTAL **MINUS** 0 X 50 S 0 **CLAIMS** INDEP MINUS ٥ X 210 5 0 CLAIMS FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM + 370 S 0 EXTENSION 2^{NO} MONTH 18 MONTH 3⁵⁰ MONTH 4TH MONTH S

Charge S_120_ to Deposit Account 50-3718. At any time during the pendency of this application, please charge any fees required or credit any over payment to Deposit Account 50-3718 pursuant to 37 CFR 1.2 5. Additionally please charge any fees to Deposit Account 50-3718 under 37 CFR 1.16, 1.17, 1.19, 1.20 and 1.21. A duplicate copy of this transmittal letter is enclosed.

1050.00

TOTAL ADDITIONAL FEE FOR THIS AMENDMENT

By

460.00

Respectfully submitted.

1640.00 OTHER FEES

R. Shane Fazzio

I hereby certify that this paper is being electronically transmitted to the Commissioner for Patents on the date shown below.

120.00

Date of Transmision; October 9, 2007

Typed Name: Thomas F. Woods

FEE

Signature:

Thomas F. Woods Attorney/Agent for Applicant(s)

120

Ö

Reg. No. 36,726

Date: October 9, 2007

Telephone No. (303) 823-6560

U.S. Patent Appln. Ser. No. 10/807,417 entitled "Microcap Wafer Bonding Apparatus" to Fazzio; Avago Technologies Attorney Docket No. 10030899-1; Woods Patent Law Docket No. P AVG 188.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: R. Shane Fazzio Examiner Name: Monica Lewis

Serial No.: 10/807,417 Group Art Unit: 2822

Filed: March 23, 2004 Attorney Docket No.: 10030899-1

Confirmation No.: 3854

Title: Microcap Wafer Bonding Apparatus

SECOND PRELIMINARY AMENDMENT AND RESPONSE TO NOTICE OF NON-COMPLIANT AMENDMENT

Commissioner for Patents P.O. Box 1450 Arlington, VA 22313-1450

Sir:

In response to the Notice of Non-Compliant Amendment dated August 29, 2007, and further to a Request for Continuing Examination submitted on August 27, 2007, Applicants respectfully request entry of the second set of preliminary amendments set forth herein, and allowance of the above-identified patent application as amended herein:

......

DATE OF DEPOSIT: October 9, 2007

<u>CERTIFICATE OF ELECTRONIC DEPOSIT</u>: I hereby certify that all paper(s) described herein are being filed electronically with the United States Patent and Trademark Office on the date indicated above and addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Printed Name: Thomas F. Woods, Reg. No. 36,726